

Device Ratings and Specifications

Part Number	Max Continuous Working Voltage -55°C to 125°C	Performance Specifications (25°C)					
		Nominal Voltage		Maximum Clamping Voltage at Specified Current (8/20µs)	Maximum ESD Clamp Voltage (Note 2)		Typical Capacitance at 1MHz
		(Note 1) $V_{M(DC)}$	V_{NOM} at 1mA DC		V_c	8kV Contact (Note 3)	
(V)	MIN (V)	MAX (V)	(V)	(V)	Clamp (V)	(pF)	
V18MLE0402N	18	22	28	50 at 1A	<125	<110	<55
V18MLE0402F (Note 8)	18	22	28	50 at 1A	<125	<110	<55
V18MLE0603N	18	22	28	50 at 1A	<75	<110	<125
V18MLE0603F (Note 8)	18	22	28	50 at 1A	<75	<110	<125
V18MLE0603LN	18	22	28	50 at 1A	<100	<140	<100
V18MLE0805N	18	22	28	50 at 1A	<70	<75	<500
V18MLE0805LN	18	22	28	50 at 1A	<75	<135	<290
V18MLE1206N	18	22	28	50 at 1A	<65	<65	<1700

NOTES:

- For applications of 18V_{DC} or less. Higher voltages available, contact your Littelfuse Sales Representative.
- Tested with IEC-61000-4-2 Human Body Model (HBM) discharge test circuit.
- Direct discharge to device terminals (IEC preferred test method).
- Corona discharge through air (represents actual ESD event).
- Capacitance may be customized, contact your Littelfuse Sales Representative.
- Leakage current ratings are at 18 V_{DC} and 25µA maximum.
- The typical capacitance rating is the discrete component test result.
- Items are lead free, and available as "R" packing option only.

Peak Current and Energy Derating Curve

For applications exceeding 125°C ambient temperature, the peak surge current and energy ratings must be reduced as shown below.

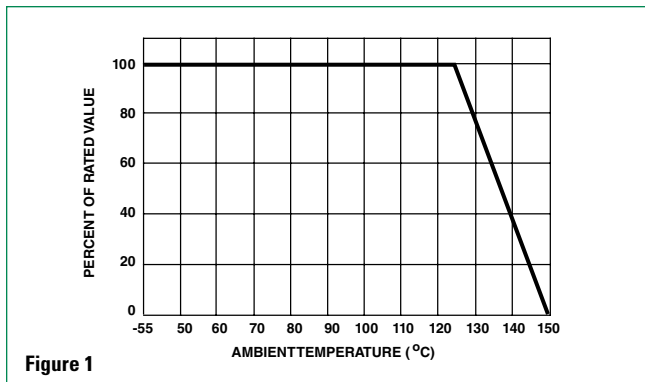


Figure 1

Nominal Voltage Stability to Multiple ESD Impulses (8kV Contact Discharges per IEC 61000-4-2)

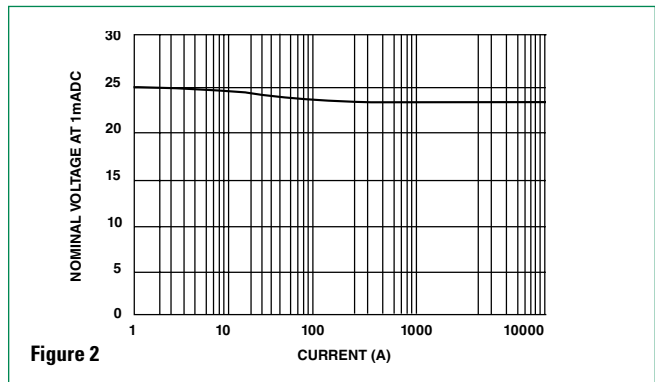


Figure 2

Standby Current at Normalized Varistor Voltage and Temperature

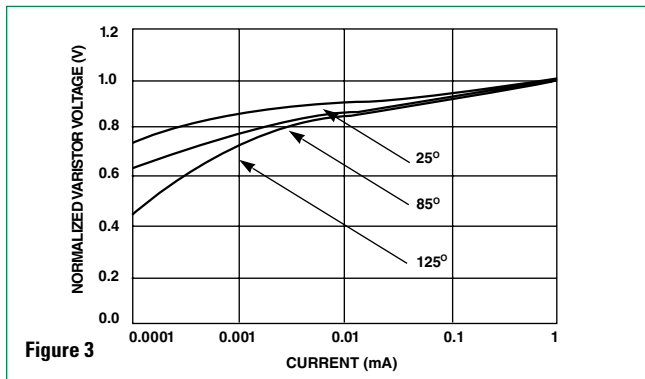


Figure 3

Impedance (Z) vs Frequency Typical Characteristic

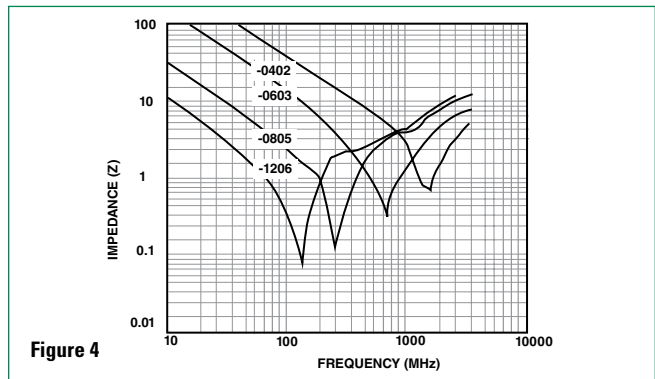


Figure 4

Device Characteristics

At low current levels, the V-I curve of the multilayer transient voltage suppressor approaches a linear (ohmic) relationship and shows a temperature dependent effect. At or below the maximum working voltage, the suppressor is in a high resistance model (approaching $10^6\Omega$ at its maximum rated voltage). Leakage currents at maximum rated voltage are below $100\mu A$, typically $25\mu A$; for 0402 size below $20\mu A$, typically $5\mu A$.

Typical Temperature Dependence of the Characteristic Curve in the Leakage Region

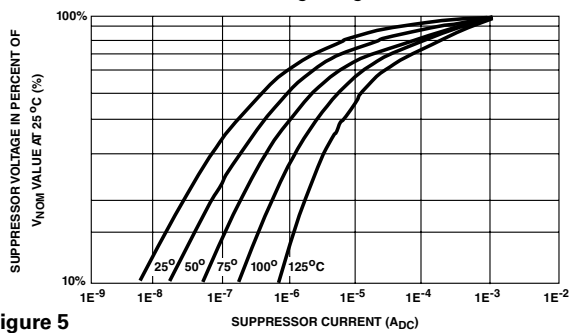


Figure 5

Speed of Response

The Multilayer Suppressor is a leadless device. Its response time is not limited by the parasitic lead inductances found in other surface mount packages. The response time of the $Z_{N}O$ dielectric material is less than 1ns and the MLE can clamp very fast dV/dT events such as ESD. Additionally, in "real world" applications, the associated circuit wiring is often the greatest factor effecting speed of response. Therefore, transient suppressor placement within a circuit can be considered important in certain instances.

Multilayer Internal Construction

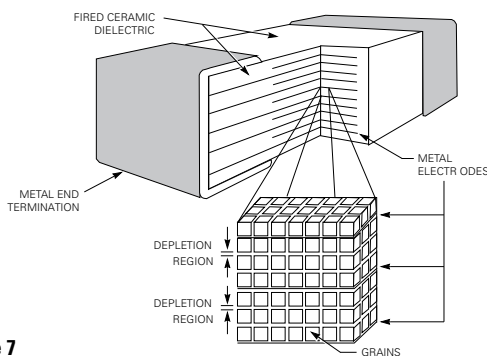


Figure 7

Clamping Voltage Over Temperature (V_c at 10A)

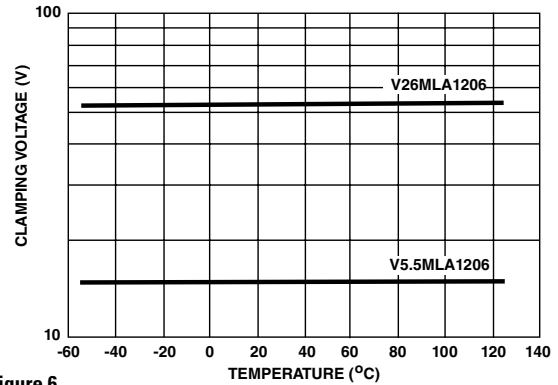


Figure 6

Energy Absorption/Peak Current Capability

Energy dissipated within the MLE is calculated by multiplying the clamping voltage, transient current and transient duration. An important advantage of the multilayer is its interdigitated electrode construction within the mass of dielectric material. This results in excellent current distribution and the peak temperature per energy absorbed is very low. The matrix of semiconducting grains combine to absorb and distribute transient energy (heat) (see Speed of Response). This dramatically reduces peak temperature; thermal stresses and enhances device reliability.

As a measure of the device capability in energy and peak current handling, the V26MLA1206A part was tested with multiple pulses at its peak current rating (3A, 8/20 μs). At the end of the test, 10,000 pulses later, the device voltage characteristics are still well within specification.

Repetitive Pulse Capability

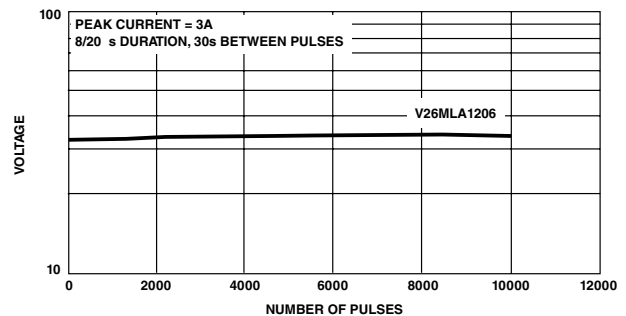


Figure 8

Lead (Pb) Soldering Recommendations

The principal techniques used for the soldering of components in surface mount technology are IR Re-flow and Wave soldering. Typical profiles are shown on the right.

The recommended solder for the MLE suppressor is a 62/36/2 (Sn/Pb/Ag), 60/40 (Sn/Pb) or 63/37 (Sn/Pb). Littelfuse also recommends an RMA solder flux.

Wave soldering is the most strenuous of the processes. To avoid the possibility of generating stresses due to thermal shock, a preheat stage in the soldering process is recommended, and the peak temperature of the solder process should be rigidly controlled.

When using a reflow process, care should be taken to ensure that the MLE chip is not subjected to a thermal gradient steeper than 4 degrees per second; the ideal gradient being 2 degrees per second. During the soldering process, preheating to within 100 degrees of the solder's peak temperature is essential to minimize thermal shock.

Once the soldering process has been completed, it is still necessary to ensure that any further thermal shocks are avoided. One possible cause of thermal shock is hot printed circuit boards being removed from the solder process and subjected to cleaning solvents at room temperature. The boards must be allowed to cool gradually to less than 50°C before cleaning.

Reflow Solder Profile

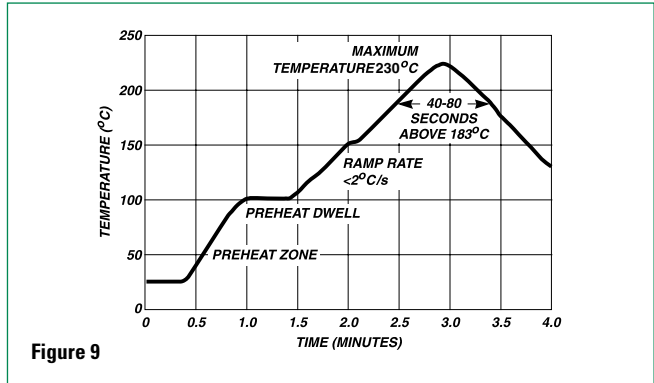


Figure 9

Wave Solder Profile

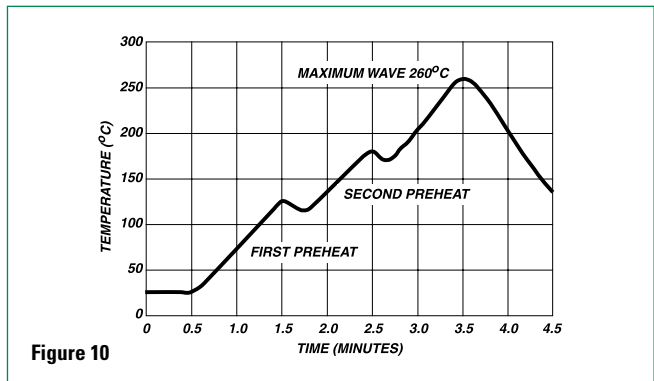


Figure 10

Lead-free (Pb-free) Soldering Recommendations

Littelfuse offers the Nickel Barrier Termination finish for the optimum Lead-free solder performance.

The preferred solder is 96.5/3.0/0.5 (SnAgCu) with an RMA flux, but there is a wide selection of pastes and fluxes available with which the Nickel Barrier parts should be compatible.

The reflow profile must be constrained by the maximums in the Lead-free Reflow Profile. For Lead-free Wave soldering, the Wave Solder Profile still applies.

Note: the Lead-free paste, flux and profile were used for evaluation purposes by Littelfuse, based upon industry standards and practices. There are multiple choices of all three available, it is advised that the customer explores the optimum combination for their process as processes vary considerably from site to site.

Lead-free Re-flow Profile

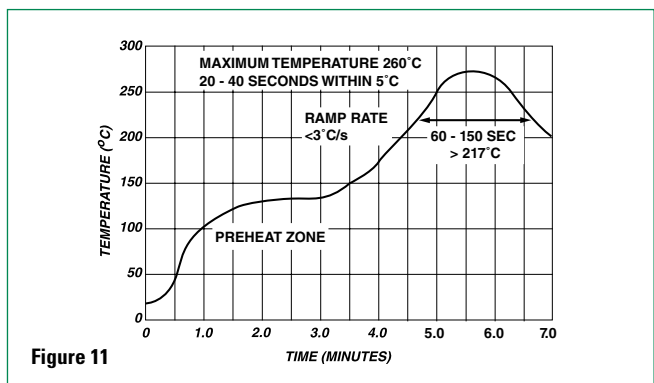
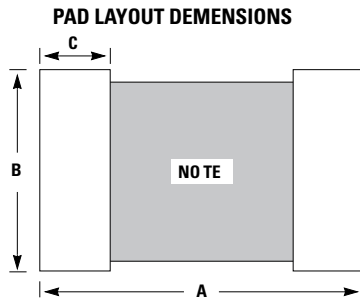
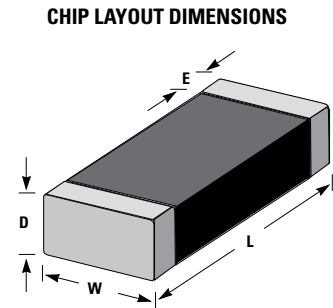


Figure 11

Product Dimensions (mm)

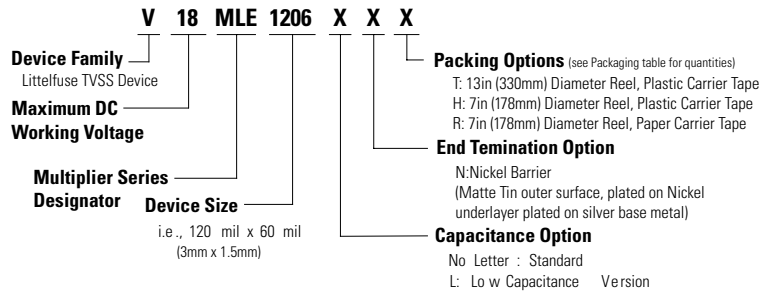


Note: Avoid metal runs in this area, parts are not recommended for use in applications using Silver (Ag) epoxy paste.



Dimension	1206 Size		0805 Size		0603 Size		0402 Size	
	IN	MM	IN	MM	IN	MM	IN	MM
A	0.160	4.06	0.120	3.05	0.100	2.54	0.067	1.70
B	0.065	1.65	0.050	1.27	0.030	0.76	0.020	0.51
C	0.040	1.02	0.040	1.02	0.035	0.89	0.024	0.61
D (max.)	0.071	1.80	0.043	1.10	0.040	1.00	0.024	0.60
E	0.02 +/- 0.01	0.50 +/- 0.25	0.02 +/- 0.01	0.50 +/- 0.25	0.015 +/- 0.008	0.4 +/- 0.2	0.010 +/- 0.006	0.25 +/- 0.15
L	0.125 +/- 0.012	3.20 +/- 0.03	0.079 +/- 0.008	2.01 +/- 0.2	0.063 +/- 0.006	1.6 +/- 0.15	0.039 +/- 0.004	1.0 +/- 0.1
W	0.06 +/- 0.011	1.60 +/- 0.28	0.049 +/- 0.008	1.25 +/- 0.2	0.032 +/- 0.006	0.8 +/- 0.15	0.020 +/- 0.004	0.5 +/- 0.1

Part Numbering System

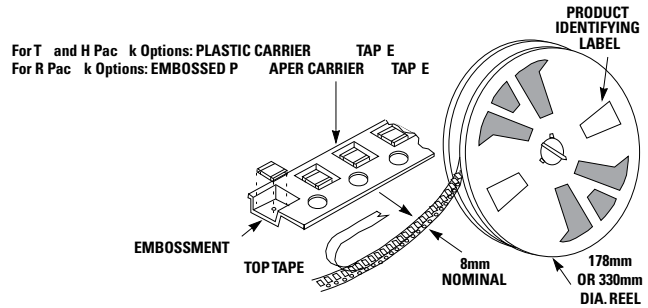
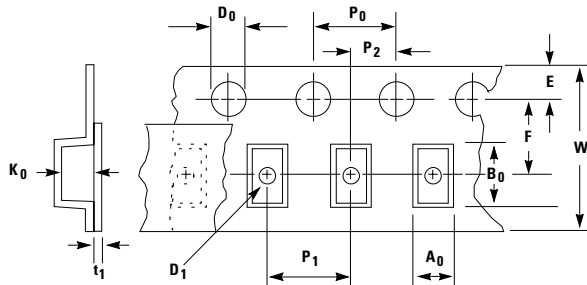


Packaging*

Device Size	Quantity			
	13" Inch Reel ('T' Option)	7" Inch Reel ('H' Option)	7" Inch Reel ('R' Option)	Bulk Pack ('A' Option)
1206	10,000	2,500	N/A	2500
0805	10,000	2,500	N/A	2500
0603	10,000	2,500	4,000	2500
0402	N/A	N/A	10,000	N/A

*(Packaging) It is recommended that parts be kept in the sealed bag provided and that parts be used as soon as possible when removed from bags.

Tape and Reel Specifications



Symbol	Description	Dimensions in Millimeters	
		0402 Size	0603, 0805 & 1206 Sizes
A ₀	Width of Cavity	Dependent on Chip Size to Minimize Rotation.	
B ₀	Length of Cavity	Dependent on Chip Size to Minimize Rotation.	
K ₀	Depth of Cavity	Dependent on Chip Size to Minimize Rotation.	
W	Width of Tape	8 +/- 0.2	8 +/- 0.3
F	Distance Between Drive Hole Centers and Cavity Centers	3.5 +/- 0.05	3.5 +/- 0.05
E	Distance Between Drive Hole Centers and Tape Edge	1.75 +/- 0.1	1.75 +/- 0.1
P ₁	Distance Between Cavity Centers	2 +/- 0.05	4 +/- 0.1
P ₂	Axial Drive Distance Between Drive Hole Centers & Cavity Centers	2 +/- 0.1	2 +/- 0.1
P ₀	Axial Drive Distance Between Drive Hole Centers	4 +/- 0.1	4 +/- 0.1
D ₀	Drive Hole Diameter	1.55 +/- 0.05	1.55 +/- 0.05
D ₁	Diameter of Cavity Piercing	N/A	1.05 +/- 0.05
T ₁	Top Tape Thickness	0.1 Max	0.1 Max

Notes :

- Conforms to EIA-481-1, Revision A
- Can be supplied to IEC publication 286-3

Mouser Electronics

Authorized Distributor

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[V18MLE0603NT](#) [V18MLE0603WH](#) [V18MLE0603WA](#) [V18MLE0603A](#) [V18MLE1206WT](#) [V18MLE1206NT](#)
[V18MLE0805NH](#) [V18MLE0603T](#) [V18MLE1206H](#) [V18MLE0603H](#) [V18MLE0805NT](#) [V18MLE1206NA](#)
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